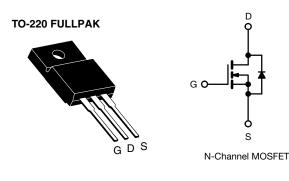
SiHF080N60E



Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.070			
Q _g max. (nC)	63				
Q _{gs} (nC)	19				
Q _{gd} (nC)	10				
Configuration	Single				

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SIHF080N60E-GE3

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	- v	
Gate-source voltage			V _{GS}	± 30		
Continuous drain current (T _J = 150 °C) $^{\circ}$	V _{GS} at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	1-	14		
	VGS at TO V	T _C = 100 °C	l _D	9	А	
Pulsed drain current ^a			I _{DM}	96		
Linear derating factor				0.28	W/°C	
Single pulse avalanche energy ^b		E _{AS}	226	mJ		
Maximum power dissipation			PD	35	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope		T _J = 125 °C		100		
Reverse diode dv/dt d	•		dv/dt	10	V/ns	
Soldering recommendations (peak temperature) ^c	For	10 s		260	°C	
Mounting torque, M3 screw	•			0.6	Nm	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4.0 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

e. Limited by maximum junction temperature

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THERMAL RESISTANCE RAT	INGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	- 65			°C/W			
Maximum junction-to-case (drain)	R _{thJC}	- 3.6				-C/W		
SPECIFICATIONS (T _J = 25 $^{\circ}$ C,	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 μΑ	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 µA	3.0	-	5.0	V
Gate-source leakage		$V_{GS} = \pm 20 \text{ V}$			-	-	± 100	nA
	I _{GSS}	$V_{GS} = \pm 30 \text{ V}$			-	-	± 1	μA
Zero gate voltage drain current		$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			-	-	1	
	IDSS	V _{DS} = 480 V	', V _{GS} = 0 √	′, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 V$	١	₀ = 17 A	-	0.070	0.080	Ω
Forward transconductance a	9 _{fs}	V _{DS}	= 20 V, I _D =	= 17 A	-	4.6	-	S
Dynamic	-				•	•		
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	2557	-	pF	
Output capacitance	C _{oss}			-	105	-		
Reverse transfer capacitance	C _{rss}			-	6	-		
Effective output capacitance, energy related ^a	C _{o(er)}	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	79	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	499	-		
Total gate charge	Qg				-	42	63	
Gate-source charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		-	19	-	nC	
Gate-drain charge	Q _{gd}				-	10	-	
Turn-on delay time	t _{d(on)}	$V_{DD} = 480 \text{ V}, \text{ I}_D = 17 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$		-	31	62	- ns	
Rise time	t _r			-	96	144		
Turn-off delay time	t _{d(off)}			-	37	74		
Fall time	t _f			-	31	62		
Gate input resistance	R _g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω	
Drain-Source Body Diode Characterist		•			•		•	
Continuous source-drain diode current	IS	MOSFET symbol showing the integral reverse p - n junction diode		-	-	35	A	
Pulsed diode forward current	I _{SM}			-	-	96		
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 17 \text{ A},$ di/dt = 80 A/µs, V _R = 25 V		- 1	441	882	ns	
Reverse recovery charge	Q _{rr}			-	5.2	10.4	μC	
Reverse recovery current	I _{RRM}			-	21	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

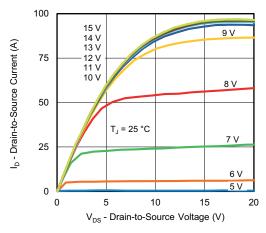


Fig. 1 - Typical Output Characteristics

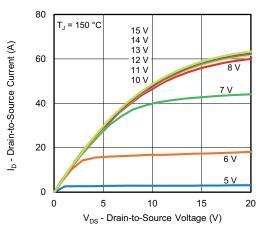


Fig. 2 - Typical Output Characteristics

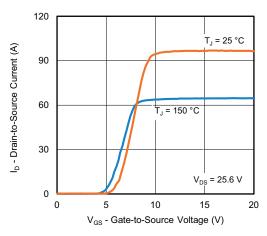


Fig. 3 - Typical Transfer Characteristics

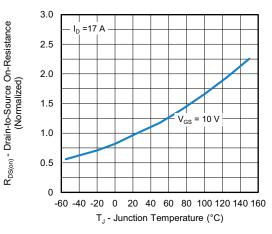


Fig. 4 - Normalized On-Resistance vs. Temperature

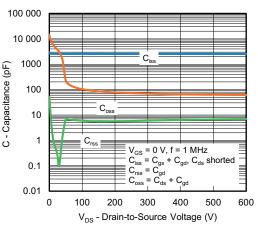


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

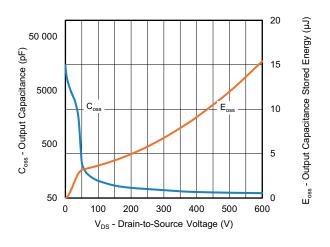


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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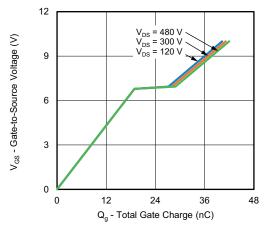


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

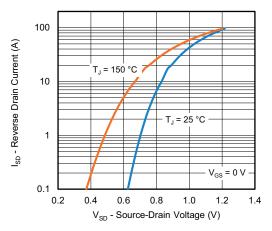


Fig. 8 - Typical Source-Drain Diode Forward Voltage

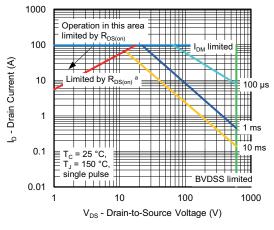


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

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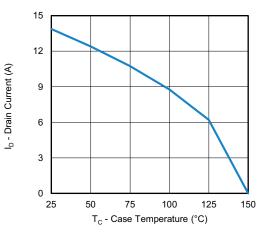


Fig. 10 - Maximum Drain Current vs. Case Temperature

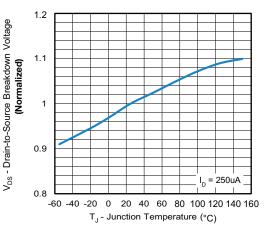
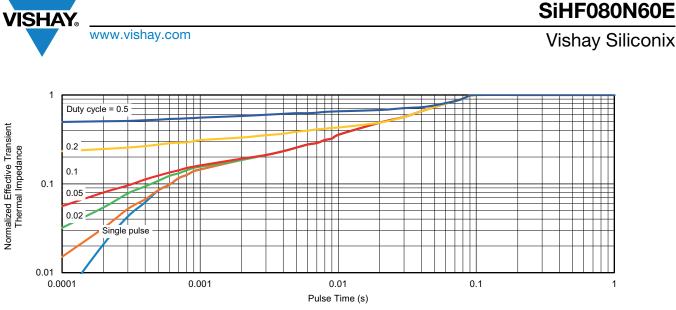


Fig. 11 - Temperature vs. Drain-to-Source Voltage





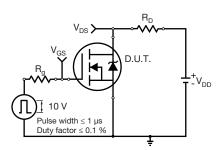


Fig. 13 - Switching Time Test Circuit

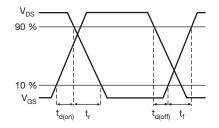


Fig. 14 - Switching Time Waveforms

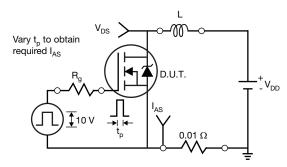


Fig. 15 - Unclamped Inductive Test Circuit

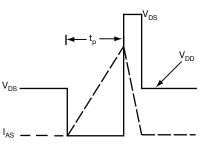


Fig. 16 - Unclamped Inductive Waveforms

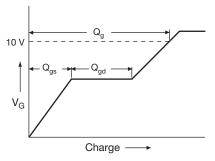


Fig. 17 - Basic Gate Charge Waveform

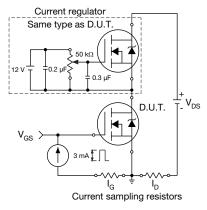


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dv/dt Test Circuit

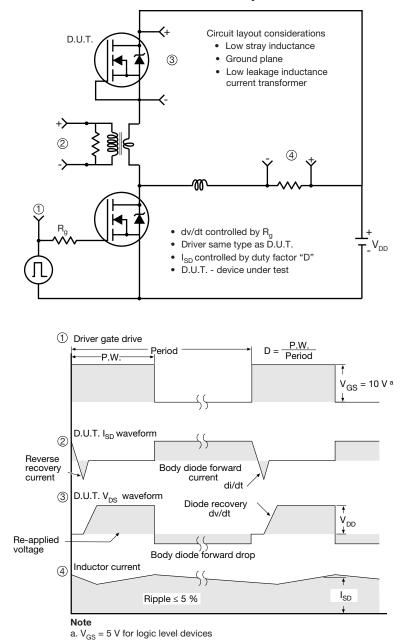


Fig. 19 - For N-Channel

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